

Cardinal Circuit

Used Samsung CP60L – *Technical Specifications*

Placing up to 36,000 chip/ hour, designed with 6 heads and 12 nozzles is predominant in placing chips with precision and speed. It's compact footprint and structural design technology minimizes vibration to ensure reliability.

Alignment unit: Line CCD

PCB Size: Maximum: 500 x 400 x 50
Minimum: 50x50x0.4

Placement Rate (tact time): Chip (sec/chip): 0.096
QFP (sec/QFP): 0.85 (by vision)

Feeder Capacity: 116ea (8mm tape feeder)

Feeder Type: Tape Type: 8, 12, 16, 24, 32, 44, 56 Tape Feeder/Intelligent Feeder System /Bulk Feeder, Belt Stick Feeder (stack, multi) Vibratory Stick Feeder (multi), Tray Feeder (1 step, 20 step, 40 step, shuttle type)

Conveyor Direction: Left to Right. (L-R option)

Placement Accuracy: Chip (mm) +/- 0.08mm (3Sigma), 0603
QFP (mm) +/- 0.065 (By vision)

Applicable Components: Chip: 1005 Chip ~ 9mm (32mm), (option: 0603 chip)
IC Type: QFP: 32mm (0.6 pitch)
BGA: 30mm (1.0 pitch)
Work Components: CHIP, SOP, QFP, BGA

External Dimension: 1,700 x 1,870 x 1,470 (L x W x H, mm)

Power Supply: AC110, 220V (50/60Hz) 7.7KW

Net Weight: 1,800Kg.

Head: Head No: 6 Head x 2
Align Size: 20 x 20

Application: Placement Rate: 18,000~36,000 CPH
Applicable Components: 0603, 1005~, TR MELF, Tantalum, ALEC, SOP